

### Information for Lot 9 of ErP (Ecodesign)

This addendum addresses European Union (EU) Ecodesign requirements for servers and storage products. All data and ratings within this addendum are in reference only to the Supermicro product(s) in the manual. The below information conforms to requirements laid down in Annex II of the Commission Regulation 2019/424.

- 3(1)(a): See Section 1.1 of the system manual for the product type.
- 3(1)(b): See the title page and preface of the system manual for the trademark and manufacturer's address.
- 3(1)(c): See the title page of the system manual for product model number(s).
- 3(1)(d): See the serial number on the physical system to determine the year of manufacture.
- 3(1)(e-j): **PSU Efficiency and Power Factor Value (Table) (From 80 Plus report)**

<b>PSU Model #: PWS-3K02G-2R Watts: 3000W</b>	<b>PSU Efficiency</b>				<b>Power Factor</b>
<b>% of Rated Load</b>	<b>10 %</b>	<b>20 %</b>	<b>50 %</b>	<b>100 %</b>	<b>50 %</b>
Single Output (AC-DC)	90 %	94 %	96 %	94 %	>0.98

#### System (EUT) Efficiency in **Idle State** Power (Table)

<b>Representative Configurations</b>	<b>Measured Idle State Power (W)</b>	<b>Calculated Idle Power Allowance (W)</b>
High-End Performance Configuration	633.3	724.76
Typical Configuration	N/A	N/A
Low-End Performance Configuration	434.7	274.52

#### System (EUT) Efficiency in **Active State** Power (Table)

<b>Representative Configurations</b>	<b>Active State Efficiency Score (Effserver)</b>	<b>Minimum Active State Efficiency for 2-Socket Server</b>
High-End Performance Configuration	26.4	9.5
Typical Configuration	N/A	
Low-End Performance Configuration	15.9	

3(1)(k): The operating condition class is **A2**.

Operating condition class	Dry bulb temp °C		Humidity range, non-condensing		Max dew point (°C)	Maximum rate of change (°C/hr)
	Allowable range	Recommended range	Allowable range	Recommended range		
A1	15- 32	18-27	- 12 °C Dew Point (DP) and 8 % relative humidity (RH) to 17 °C DP and 80 % RH	- 9 °C DP to 15 °C DP and 60 % RH	17	5/20
A2	10-35	18-27	- 12 °C DP and 8 % RH to 21 °C DP and	Same as A1	21	5/20
A3	5-40	18-27	- 12 °C DP and 8 % RH to 24 °C DP and	Same as A1	24	5/20
A4	5-45	18-27	- 12 °C DP and 8 % RH to 24 °C DP and	Same as A1	24	5/20

3(1)(l): The idle state power at the higher boundary temperature of the operating conditions class is 747.3 W.

3(1)(m): The active state efficiency and performance is 26.4.

3(1)(n): There are two methods by which a user can securely delete data from this system. The user performing secure data deletion should be an IT professional.

The first is with a Unified Extensible Firmware Interface (UEFI) shell utility. This utility works on X11/X12/B11/B12 motherboard series with onboard SATA/NVMe devices. Any user may access and download this utility through following link:

[https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9\\_Secure\\_Data\\_Deletion\\_UTILITY/](https://www.supermicro.com/about/policies/disclaimer.cfm?url=/wftp/utility/Lot9_Secure_Data_Deletion_UTILITY/)

Download the shell utility package and extract it to a USB flash drive, then plug the drive into the server for which secure data deletion is necessary. Then turn the system on. Navigate to the BIOS setup menu, and then place the server system into the UEFI shell environment. Follow the instructions in the README file to invoke the utility and complete the deletion.

The second method is through the secure data deletion tool provided by the original manufacturer of the hard drive. This should be used in a scenario where the shell utility is not applicable. Each manufacturer should have the tool available on their website. If needed, please look on the hard drive label for the name of the manufacturer and model information.

3(1)(o): List of recommended combinations of blade servers with chassis: N/A.

3(1)(p): List of all current SKUs within this product family: SYS-220GQ-TNAR+.

3(3)(a): There is no use of cobalt in batteries in this product.

The indicative weight range of neodymium in the HDD is 0.0 if manufactured by Western Digital, and is between 5-25 grams if manufactured by Seagate.

3(3)(b): Please see the disassembly instructions on the next page.

## Illustrated System Disassembly Instructions

*Please note: All the illustrations in the below disassembly instructions are for demonstration only. Components shown here may not match exactly with the components in your system.*

**CAUTION: Always power off the system and unplug the power cord(s) first before disassembling the system!**

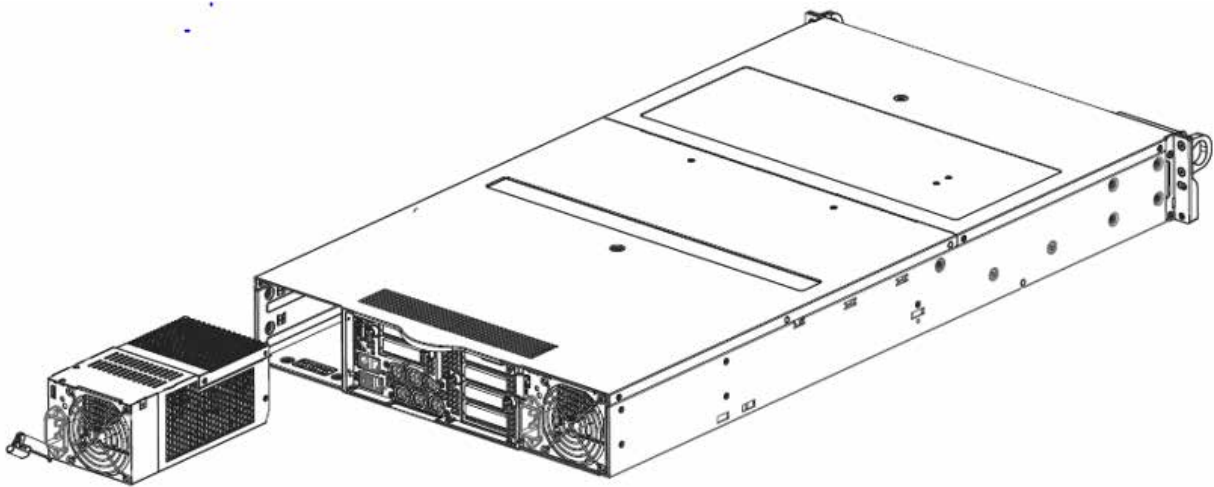
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### 1. Power Supply Module

*Type and number of fastenings:* One (1) latch per module.

*Tools required:* None.

*Procedure:* Unplug the power cord from the power supply. Push the release tab on the back of the power supply module to the side and pull the module straight out.



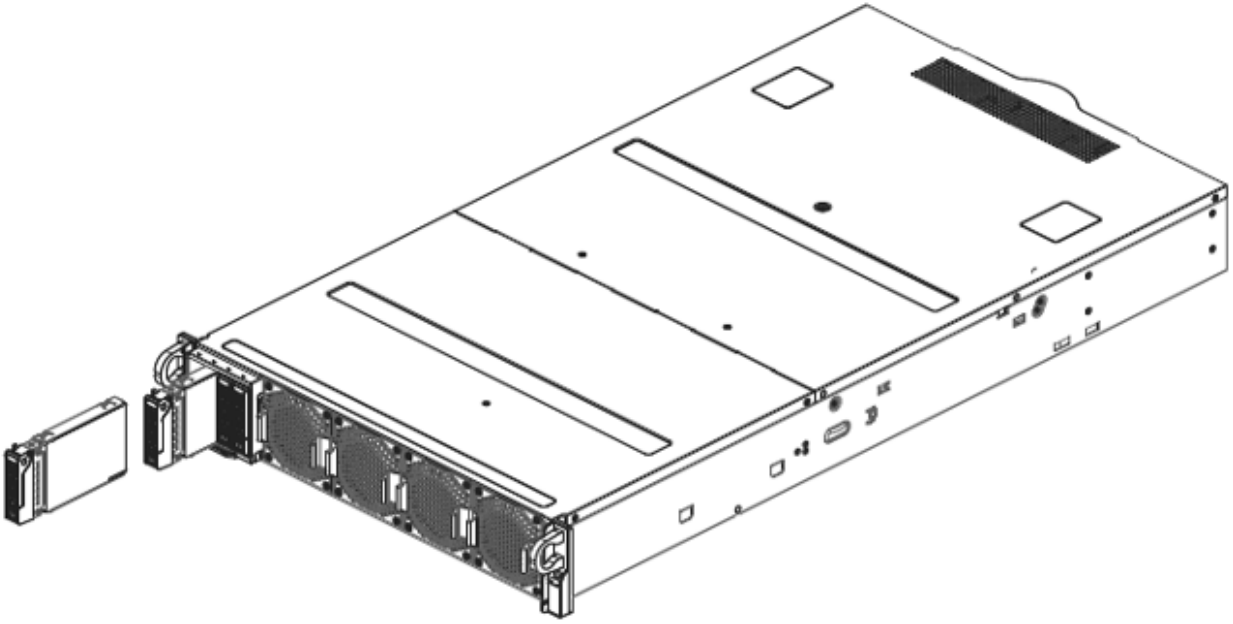
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### 2. Data Storage

*Type and number of fastenings:* One (1) locking lever.

*Tools required:* None.

*Procedure:* Lift the locking lever and pull the drive out of the chassis.



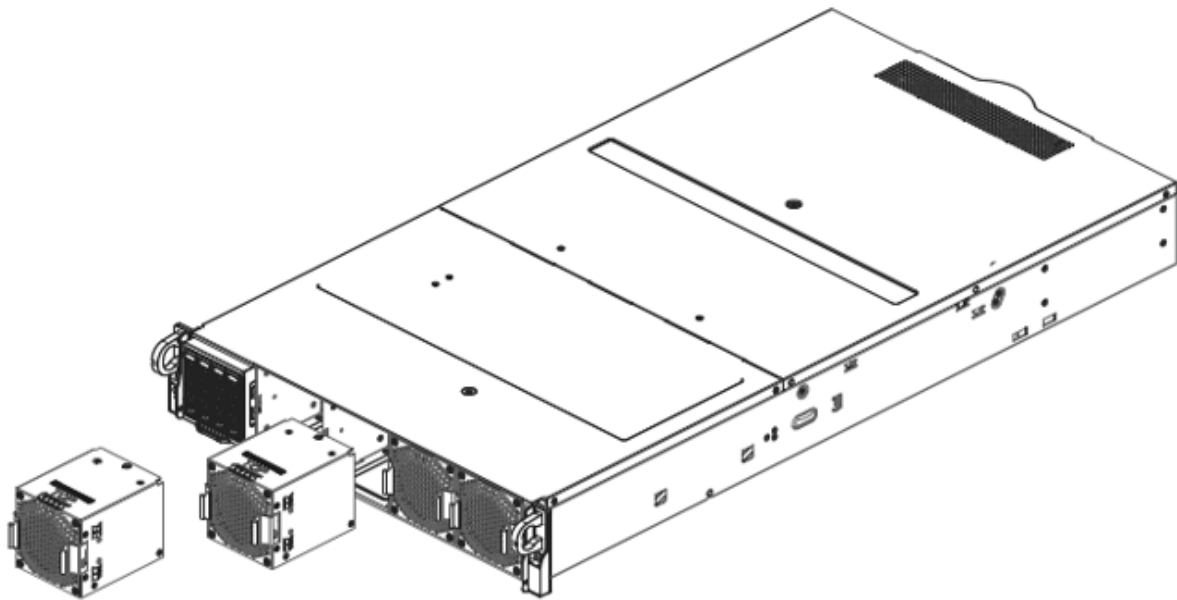
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### 3. Fans

*Type and number of fastenings:* Two (2) locking levers per fan module.

*Tools required:* None.

*Procedure:* Press the locking levers and pull the fan module out of the chassis.



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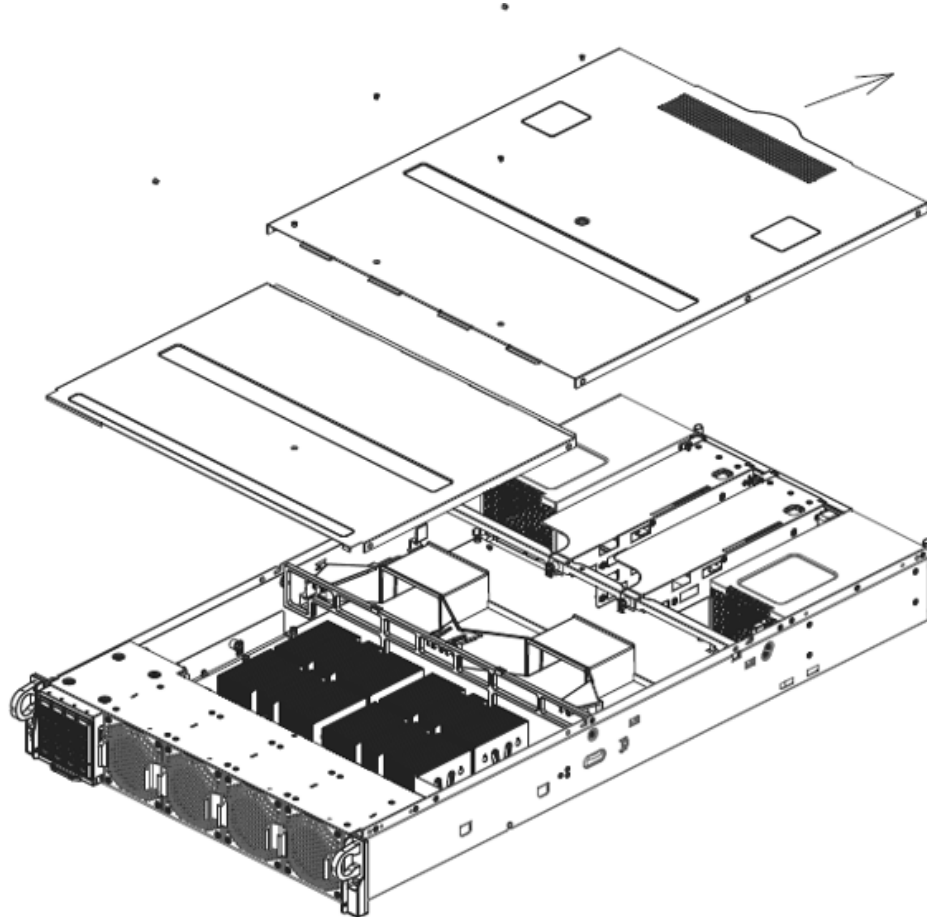
## 4. Chassis Cover

*Type and number of fastenings:* 10 screws.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:*

1. Remove the four screws on the sides and one screw on the top of the front-facing cover to release and remove the cover from the chassis.
2. Remove the two screws on the sides and three screws on the top of the rear-facing cover to release and remove the cover from the chassis.
3. Push the rear top cover toward the rear of the unit, which will separate the two top covers. Now both top covers can be removed by lifting them up.



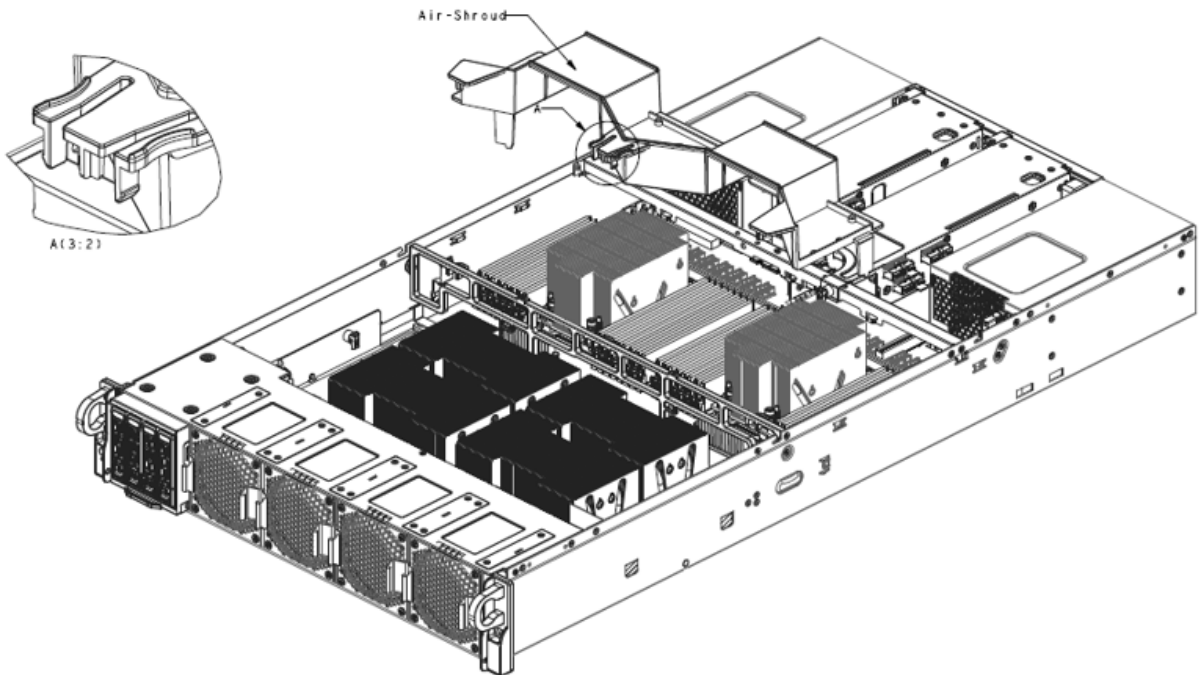
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## 5. Air Shroud

Type and number of fastenings: None

Tools required: None.

Procedure: Lift the plastic air shroud up and away from the motherboard.



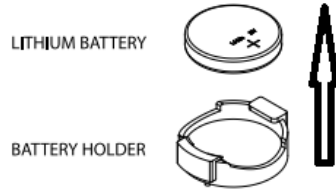
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## 6. Battery

Type and number of fastenings: One (1) latch.

Tools required: None.

Procedure: Push aside the small clamp that covers the edge of the battery. When the battery is released, lift it out of the holder.

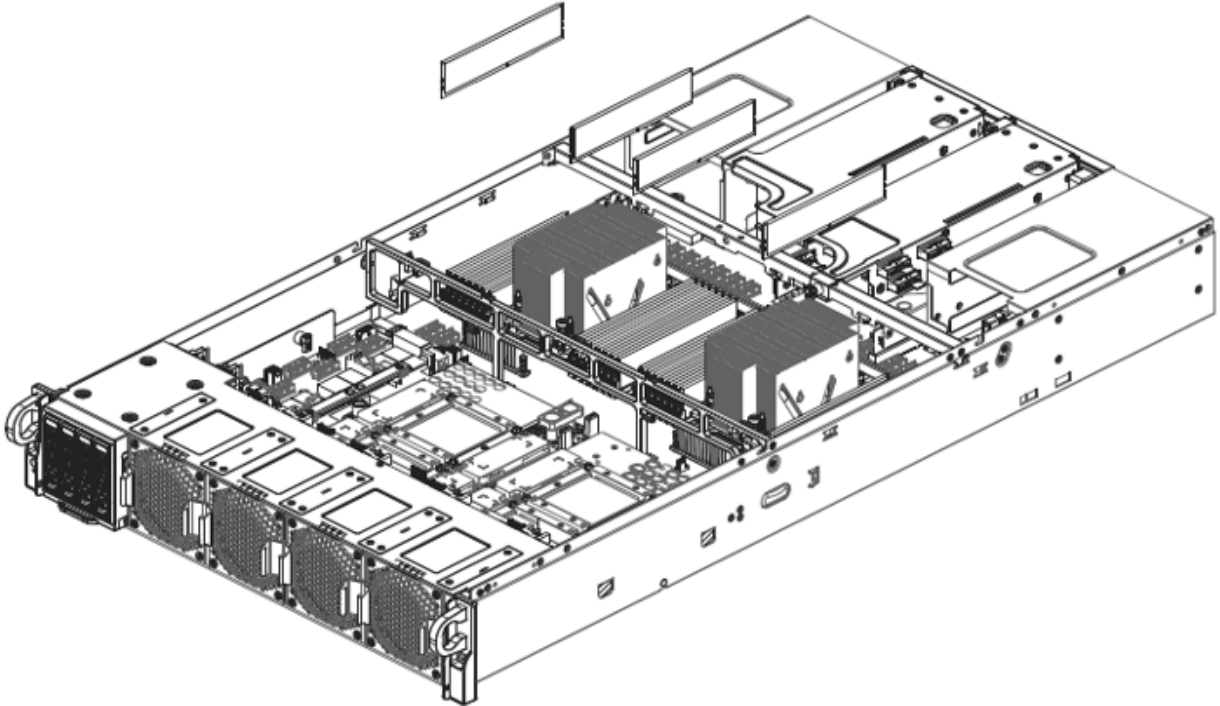


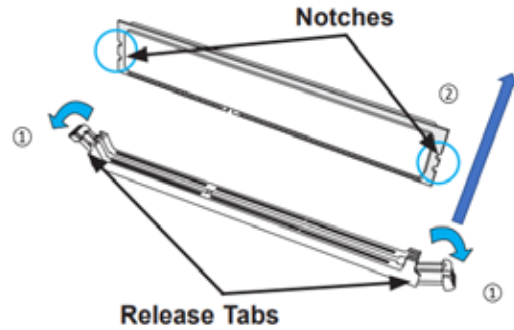
## 7. Memory

Type and number of fastenings: Two (2) latches per memory module.

Tools required: None.

Procedure: Press both release tabs on the ends of the memory module to unlock it. Once the module is loosened, remove it from the memory slot.





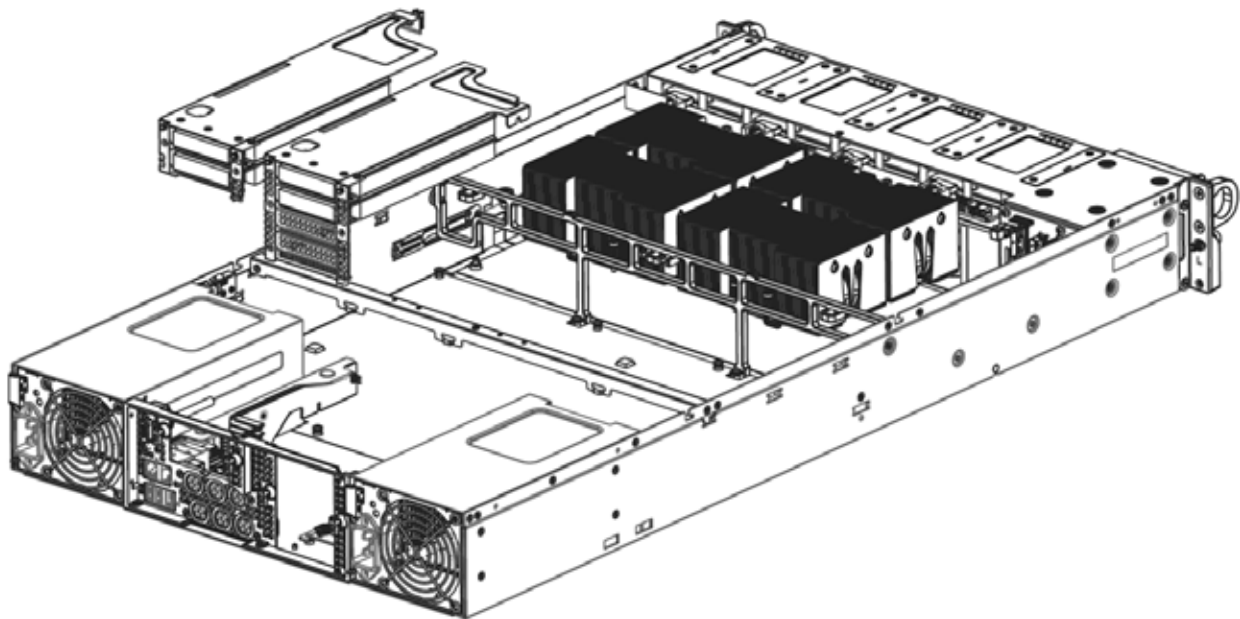
## 8. Rear Riser Assemblies

Type and number of fastenings: None.

Tools required: None.

Procedure:

1. At the rear of the chassis, remove the riser assemblies from left to right (when viewed from the rear) by unlatching the riser release at five (5) locations. There are four riser releases at the rear of the chassis and one riser release located at the metal chassis rear crossbar of the left riser assembly.
2. Slide the PCI riser out of the expansion slot from the back of the chassis by lifting each riser assembly vertically. Be careful not to damage the power or data cables attached to the assemblies. The cables can be detached if necessary; however, please note the cable numbers and their mated connectors to be able to reattach them properly.



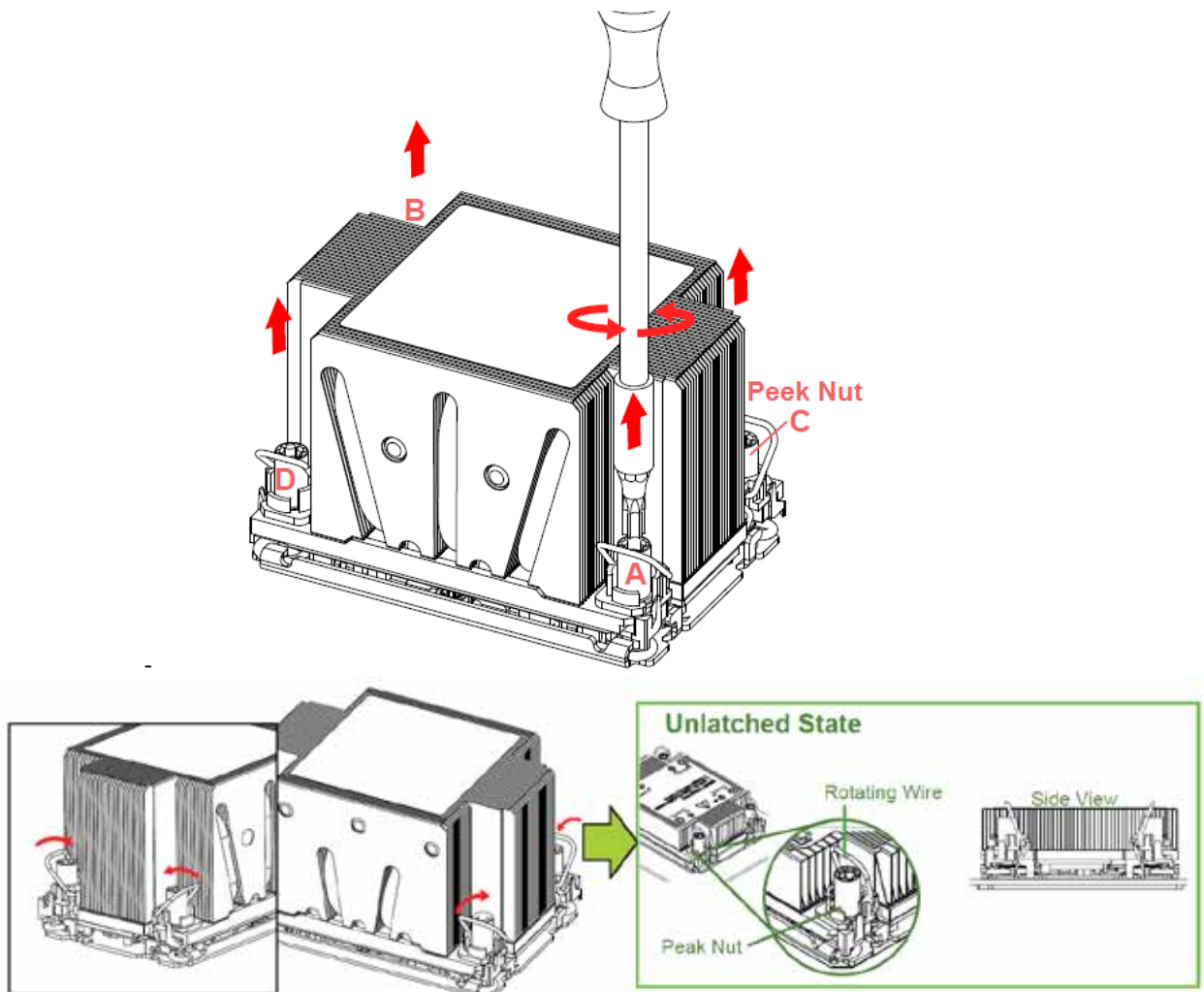
## 9. Processor and Heatsink

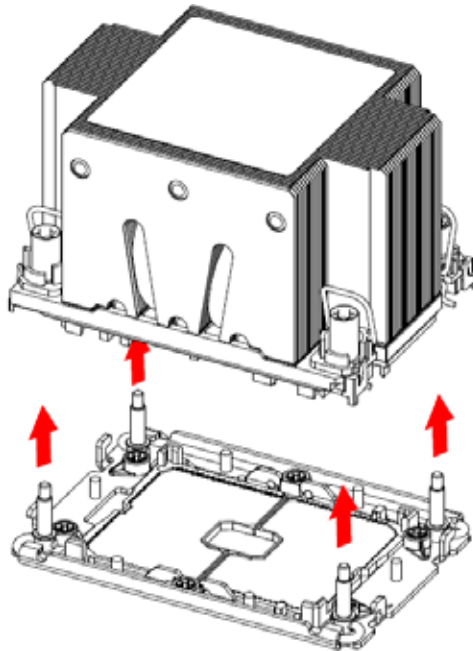
Type and number of fastenings: Four (4) T30 Torx screws.

Tools required: Screwdriver with T30 Torx bit.

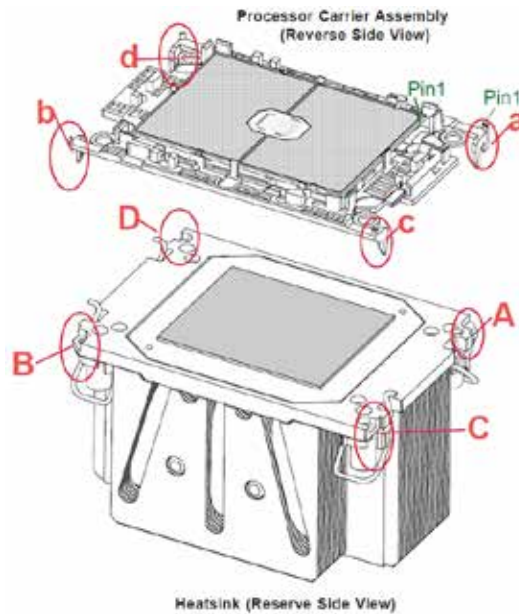
Procedure:

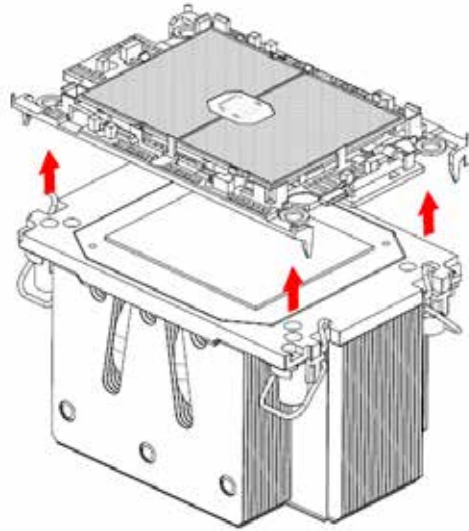
1. Loosen the four peek nuts on the heatsink in the sequence of #A, #B, #C, and #D.
2. Once the peek nuts are loosened from the CPU socket, press the rotating wires inward to unlatch the processor heatsink module from the socket.
3. Gently lift the processor heatsink module upward to remove it from the CPU socket.



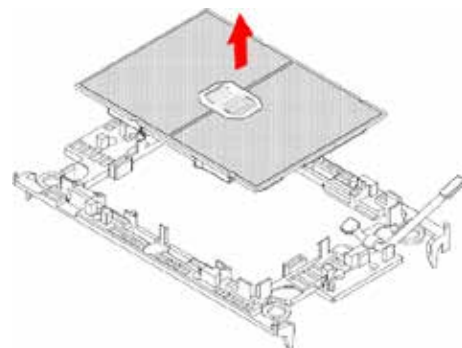
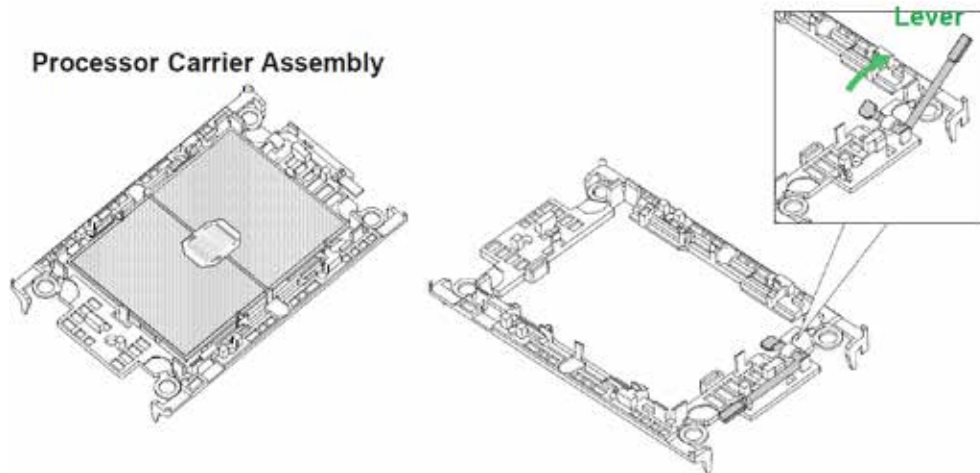


4. Detach four plastic clips (marked a, b, c, and d below) on the processor carrier assembly from the four corners of heatsink (marked A, B, C, and D below).
5. Once all plastic clips are detached from the heatsink, remove the processor carrier assembly from the heatsink.





6. Unlock the lever from its locking position and push the lever upward to disengage the processor from the processor carrier.
7. Once the processor is loosened from the carrier, carefully remove the processor from the processor carrier. *Note: To avoid damaging the processor and its pins, please handle the processor with care.*



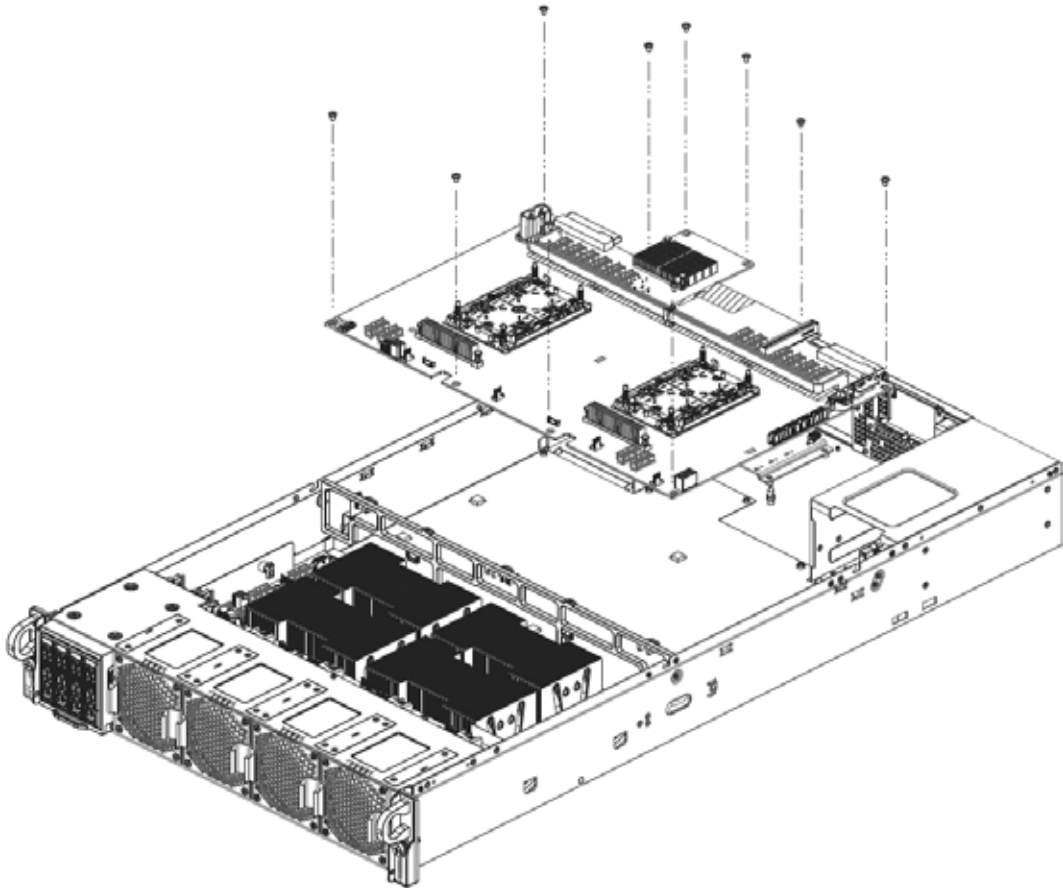
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## 10. Motherboard

Type and number of fastenings: 10 Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Remove the screws and lift the motherboard from its base.



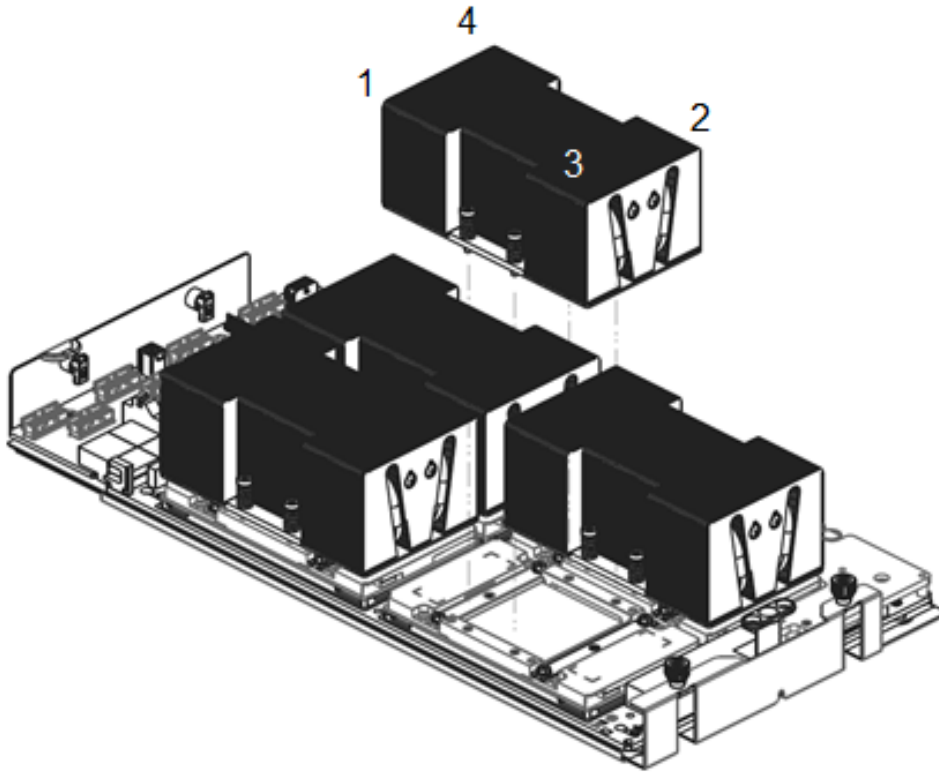
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## 11. GPU Heatsink

Type and number of fastenings: Four (4) Phillips screws.

Tools required: Screwdriver with PH2 bit.

*Procedure:* Remove the screws in the sequence of 4, 3, 2, and 1, as marked below. Lift the heatsink up and away from the GPU board.



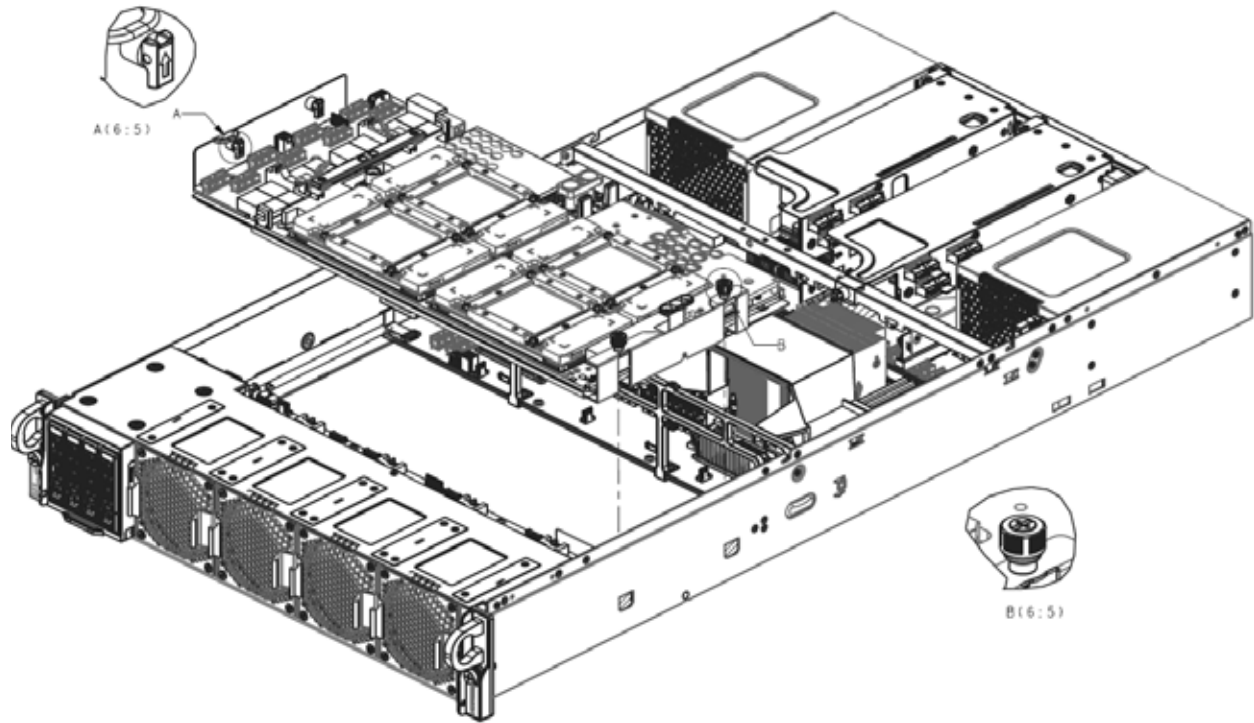
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## 12. GPU Tray

*Type and number of fastenings:* Two (2) Philip screws, and two (2) latches.

*Tools required:* Screwdriver with PH2 bit.

*Procedure:* Loosen the screws, unlock the latches, and lift the GPU Tray from its base.



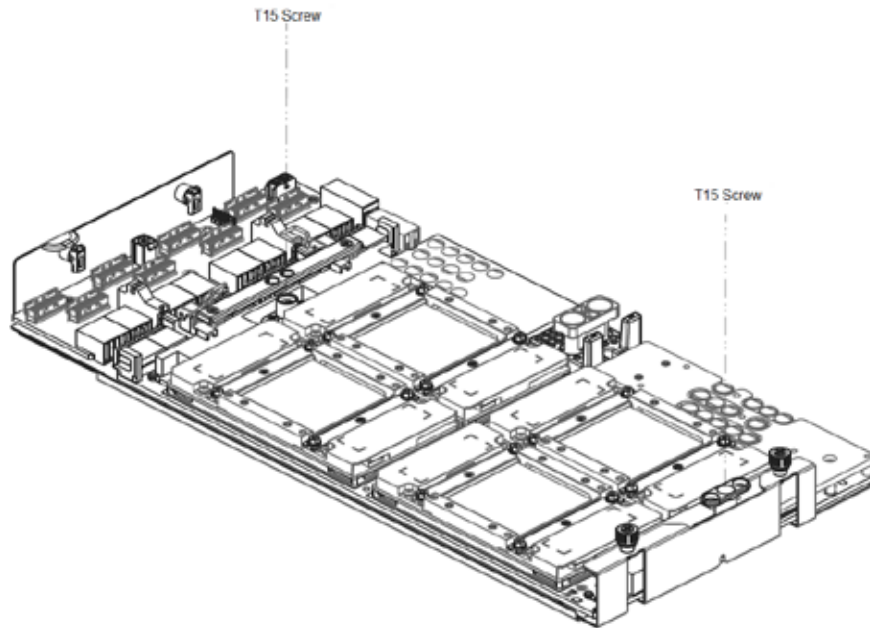
### 13. GPU Baseboard

*Type and number of fastenings:* Two (2) T15 Torx screws.

*Tools required:* Screwdriver with T15 Torx bit.

*Procedure:*

1. Loosen the T15 Torx screws.
2. Release the ball latch, which separates the GPU baseboard from the PCIe transition board assembly. The GPU baseboard will be loosened.
3. Hold the "T" handle with one hand while lifting the ball latch at the other end of the baseboard. Lift the baseboard out.



#### 14. PCIe Transition Board

Type and number of fastenings: Four (4) Phillips screws.

Tools required: Screwdriver with PH2 bit.

Procedure: Remove the screws and lift the PCIe transition board from the chassis.

